

Abstract:

A semiconductor power module (1) comprises at least a substrate (2) including at least a semiconductor element (6, 7, 8) and a pressing device (40) which acts on the substrate (2). The pressing device (40) enables to press the substrate (2), when mounted, on a cooling element (30) so as to evacuate from semiconductor components operational heat losses. The pressing device (40) consists of a housing (10) provided with at least an elastic deformation zone (16, 17, 15, 18, 19).